

014234765

WPI Acc No: 2002-055463/200207

XRAM Acc No: C02-015879

Method of bonding adherend, comprising coating on to substrate a composition containing polyoxyalkylene, saturated hydrocarbon polymer, copolymer of alkylacrylate and/or methylacrylate and epoxy resin, and laminate adherent on substrate

Patent Assignee: KANEKA CORP (KANF)

Inventor: ANDO K; KAWAKUBO F; TAKASE J

Number of Countries: 022 Number of Patents: 003

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
-----------	------	------	-------------	------	------	------

WO 200183629	A1	20011108	WO 2001JP3678	A	20010427	200207 B
--------------	----	----------	---------------	---	----------	----------

JP 2001311056	A	20011109	JP 2000130556	A	20000428	200207
---------------	---	----------	---------------	---	----------	--------

EP 1279709	A1	20030129	EP 2001926006	A	20010427	200310
------------	----	----------	---------------	---	----------	--------

WO 2001JP3678	A	20010427				
---------------	---	----------	--	--	--	--

Priority Applications (No Type Date): JP 2000130556 A 20000428

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
-----------	------	-----	----	----------	--------------

WO 200183629	A1	J	38	C09J-005/00	
--------------	----	---	----	-------------	--

Designated States (National): US

Designated States (Regional): AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE TR

JP 2001311056	A	13	C09J-005/00	
---------------	---	----	-------------	--

EP 1279709	A1	E	C09J-005/00	Based on patent WO 200183629
------------	----	---	-------------	------------------------------

Designated States (Regional): AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

Abstract (Basic): WO 200183629 A1

NOVELTY - A method of binding adherend comprises coating onto a substrate a composition containing one or two from (A) polyoxyalkylene having reactive Si elements, (B) saturated hydrocarbon polymer containing reactive Si groups, (C) a copolymer of alkylacrylate and/or alkylmethacrylate and (D) epoxy resin, and then laminate adherent onto the substrate without a temporary fixing.

DETAILED DESCRIPTION - A method of bonding adherend to a substrate, comprises applying to the adherent and/or the substrate a curable composition which comprises one or more members selected from:

(A) a polyoxyalkylene having reactive Si elements;

(B) a saturated hydrocarbon polymer containing reactive Si groups;

(C) a copolymer of alkylacrylate and/or alkylmethacrylate; and

(D) an epoxy resin, and then laminate adherent onto the substrate without a temporary fixing.

The composition has a viscosity according to JIS K - 7117 of 10.000 pa.s before curing using a B8U type viscometer (Rotary bob No. 7, speed

0.5 rpm, and atmosphere 23 degreesC).

An INDEPENDENT CLAIM is also included for the composition.

USE - Used in non-primer bonding of inorganic materials, metals, plastics etc.

ADVANTAGE - The adherend and the substrate can be bonded without open time or temporary fixing.

pp; 38 DwgNo 0/0

Title Terms: METHOD; BOND; COMPRISE; COATING; SUBSTRATE; COMPOSITION;

CONTAIN; POLYOXYALKYLENE; SATURATE; HYDROCARBON; POLYMER; COPOLYMER;

EPOXY; RESIN; LAMINATE; ADHERE; SUBSTRATE

Derwent Class: A21; A81; G03

International Patent Class (Main): C09J-005/00

International Patent Class (Additional): C08F-008/42; C08G-059/40;

C08G-065/336; C09J-123/26; C09J-133/06; C09J-163/00; C09J-171/02;

C09J-183/04; E04F-013/08

File Segment: CPI